



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Adrian E. Ong  
Title: Layout and Use of Bond Pads and Probe for Testing of Integrated Circuits Devices  
Application No.: 10/003,375  
Filing Date: November 15, 2001  
Examiner: Tung X. Nguyen  
Group Art Unit: 2829  
Confirmation No.: 4697  
Law Office: Sidley Austin LLP  
Mail Stop Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Examiner Nguyen:

Applicant submits nine (9) sheets of formal drawings, consisting of Figures 1, 2, 3, 4, 5, 6, 7, 8, and 9, in the above-named application. If there are any questions regarding these drawings, please call the undersigned at (415) 772-7428.

EXPRESS MAIL LABEL NO.:

Respectfully submitted,

EV 839 495 318 US

By:

Philip W. Woo  
Attorney of Record  
Registration No. 39,880  
PWW/rp

April 12, 2006

SIDLEY AUSTIN LLP  
555 California Street, Suite 2000  
San Francisco, CA 94104-1715